

PRODUCT DATA SHEET

TACFlux® 008

for Electronics Assembly and Rework

Introduction

TACFlux® 008 is an electronics-grade, no-clean, creamy flux. Its many uses include: rework and repair of various electronics assemblies and components, die-attach, SMT component-attach (including BGAs and flip-chips), BGA ball-attach, preform soldering, and virtually any application where a flux is required. Cycle time is not critical as TACFlux® may sit for hours with no reflow degradation. **TACFlux® 008** is compatible with a variety of no-clean solder pastes, including NC-SMQ71 Solder Paste and Indium9.52 Die-Attach Solder Paste.

Features

- Halogen-free for Pb-free applications
- Excellent pin-probe performance
- Wide reflow profile window under both air and nitrogen
- Excellent soldering performance and process yield
- Excellent wetting to all fresh and aged surface finishes including, but not limited to: OSP, immersion Ag, immersion Sn, and ENIG
- Low-voiding in all joints, including BGA assemblies

Properties

Test	Result
J-STD-004 (IPC-TM-650)	
Flux Type Classification	ROLO
Elemental Halogen Analysis	0%
Post-Reflow Reflux Residue (ICA Test)	<20%
Corrosion	Pass
SIR (Ohms)	Pass (>10 ⁸ @ 85°C and 85% RH)
Acid Value	100 (typical)
Flux Viscosity: Brookfield (5rpm)	500kcps (typical)
Tack Strength	240g (typical)
Maximum Peak Temperature	340°C (under nitrogen)
Storage Conditions	1 year @ 0–30°C

All information is for reference only.
Not to be used as incoming product specifications.

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From One Engineer To Another®

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Application Method

TACFlux® 008 can be dispensed in dots or lines onto the desired substrate, preform, or BGA sphere. It can also be easily screen-printed or stenciled on a desired component footprint.

Packaging

TACFlux® 008 is available in 10 and 30cc syringes. Other packaging may be available to meet specific requirements. Consult with Indium Corporation's sales team or Technical Support Engineers for details.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Material Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>



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